Electronic Acknowledgement Receipt					
EFS ID:	5531117				
Application Number:	10577173				
International Application Number:					
Confirmation Number:	1239				
Title of Invention:	Semiconductor device with plastic package molding compound, semiconductor chip and leadframe and method for producing the same				
First Named Inventor/Applicant Name:	Infineon Technologies AG				
Customer Number:	25281				
Filer:	Mark L. Gleason/Cindy Schlotz				
Filer Authorized By:	Mark L. Gleason				
Attorney Docket Number:	1441.141.101				
Receipt Date:	17-JUN-2009				
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Time Stamp:	11:28:58				
Application Type:	U.S. National Stage under 35 USC 371				

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## File Listing:

Document Number	Document Description	File Name	File Size(Bytes)/ Message Digest	Multi Part /₊zip	Pages (if appl.)
1	Information Disclosure Statement (IDS) Filed (SB/08)	SuppiD2.par	761670	no	4
			890ec2f3a30729299a61669639f7fb8ffcabb 3fd		

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2 Foreign Reference	Foreign Reference	JP1264230uspto.pdf	372520	no	6		
	31 /20 /200 <b>3</b> / 10 / 10 / 10 / 10 / 10 / 10 / 10 / 1	1299caee13c28572e579ee2111bfb1415c5 524ed					
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### New International Application Filed with the USPTO as a Receiving Office

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